

	<b><i>ITk Pixel – Outer Endcaps Loaded Local Supports</i></b>			ATLAS ITk-Pixel Project
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## Local Supports Loading for the ITk Pixel Outer Endcaps

Provided for the ITk Pixel Outer System Loaded Local Supports Preliminary Readiness Review  
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This document describes the procedures and equipment for the loading of modules and on-detector services in the ITk Pixel Outer Endcaps. It also describes the validation of these procedures and equipment.

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Distribution List

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Juliette Martin

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